

PATENT  
81790.0227

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Miki SASAKI, et al.

Serial No: 10/008,958

Filed: December 5, 2001

For: SEMICONDUCTOR DEVICE  
INCORPORATING A DICING  
TECHNIQUE FOR WAFER SEPARATION  
AND A METHOD FOR  
MANUFACTURING THE SAME (As  
Amended)

Art Unit: 2814

Examiner: Nathan W. Ha

I hereby certify that this correspondence is being facsimile transmitted to be received in the United States Patent and Trademark Office, Fax No. 703 740-4882 on February 4, 2003.

Sterling B. Mason Reg. No. 41,178

Name

Signature

February 5, 2003

Date

**RESPONSE TO OFFICE ACTION**

Assistant Commissioner for Patents  
Washington, D.C. 20231

Attention: Box Amendment

Dear Sir:

In response to the Office Action mailed October 4, 2002, the three-month statutory period during which to respond thereto being extended one month by the accompanying petition to February 4, 2003, Applicants submit the following amendments and remarks in the above-identified application.

**AMENDMENT**

Please amend the above-identified application as indicated below.

**IN THE TITLE:**

Please amend the title as follows:

— SEMICONDUCTOR DEVICE INCORPORATING A DICING TECHNIQUE FOR  
WAFER SEPARATION AND A METHOD FOR MANUFACTURING THE SAME --.

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AUG 7 2003

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